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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	eZ8
Core Size	8-Bit
Speed	20MHz
Connectivity	IrDA, UART/USART
Peripherals	Brown-out Detect/Reset, LED, LVD, POR, PWM, WDT
Number of I/O	17
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	-
Purchase URL	<a href="https://www.e-xfl.com/product-detail/zilog/z8f041ash020ec00tr">https://www.e-xfl.com/product-detail/zilog/z8f041ash020ec00tr</a>



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## **Low-Power Operational Amplifier**

The optional low-power operational amplifier (LPO) is a general-purpose amplifier primarily targeted for current sense applications. The LPO output may be routed internally to the ADC or externally to a pin.

## **Internal Precision Oscillator**

The internal precision oscillator (IPO) is a trimmable clock source that requires no external components.

## **Temperature Sensor**

The optional temperature sensor produces an analog output proportional to the device temperature. This signal can be sent to either the ADC or the analog comparator.

## **Analog Comparator**

The analog comparator compares the signal at an input pin with either an internal programmable voltage reference or a second input pin. The comparator output can be used to drive either an output pin or to generate an interrupt.

## **External Crystal Oscillator**

The crystal oscillator circuit provides highly accurate clock frequencies with the use of an external crystal, ceramic resonator or RC network.


## **Low Voltage Detector**

The low voltage detector (LVD) is able to generate an interrupt when the supply voltage drops below a user-programmable level. The LVD is available on 8-pin devices only.

## **On-Chip Debugger**

The Z8 Encore! XP<sup>®</sup> F082A Series products feature an integrated on-chip debugger (OCD) accessed via a single-pin interface. The OCD provides a rich-set of debugging capabilities, such as reading and writing registers, programming Flash memory, setting breakpoints, and executing code.

Table 2. Signal Descriptions (Continued)

Signal Mnemonic	I/O	Description
<b>Analog</b>		
ANA[7:0]	I	Analog Port. These signals are used as inputs to the analog-to-digital converter (ADC).
VREF	I/O	Analog-to-digital converter reference voltage input, or buffered output for internal reference.
<b>Low-Power Operational Amplifier (LPO)</b>		
AMPINP/AMPINN	I	LPO inputs. If enabled, these pins drive the positive and negative amplifier inputs respectively.
AMPOUT	O	LPO output. If enabled, this pin is driven by the on-chip LPO.
<b>Oscillators</b>		
XIN	I	External Crystal Input. This is the input pin to the crystal oscillator. A crystal can be connected between it and the <b>XOUT</b> pin to form the oscillator. In addition, this pin is used with external RC networks or external clock drivers to provide the system clock.
XOUT	O	External Crystal Output. This pin is the output of the crystal oscillator. A crystal can be connected between it and the <b>XIN</b> pin to form the oscillator.
<b>Clock Input</b>		
CLKIN	I	Clock Input Signal. This pin may be used to input a TTL-level signal to be used as the system clock.
<b>LED Drivers</b>		
LED	O	Direct LED drive capability. All port C pins have the capability to drive an LED without any other external components. These pins have programmable drive strengths set by the GPIO block.
<b>On-Chip Debugger</b>		
DBG	I/O	Debug. This signal is the control and data input and output to and from the On-Chip Debugger.
 <b>Caution:</b> The DBG pin is open-drain and requires a pull-up resistor to ensure proper operation.		
<b>Reset</b>		
RESET	I/O	RESET. Generates a Reset when asserted (driven Low). Also serves as a reset indicator; the Z8 Encore! XP forces this pin low when in reset. This pin is open-drain and features an enabled internal pull-up resistor.



110 = 64 cycles delay

111 = 128 cycles delay

INPCAP—Input Capture Event

This bit indicates if the most recent timer interrupt is caused by a Timer Input Capture Event.

0 = Previous timer interrupt is not a result of Timer Input Capture Event

1 = Previous timer interrupt is a result of Timer Input Capture Event

### Timer 0–1 Control Register 1

The Timer 0–1 Control (TxCTL1) registers enable/disable the timers, set the prescaler value, and determine the timer operating mode (Table 49).

**Table 49. Timer 0–1 Control Register 1 (TxCTL1)**

BITS	7	6	5	4	3	2	1	0
FIELD	TEN	TPOL	PRES			TMODE		
RESET	0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
ADDR	F07H, F0FH							

TEN—Timer Enable

0 = Timer is disabled.

1 = Timer enabled to count.

TPOL—Timer Input/Output Polarity

Operation of this bit is a function of the current operating mode of the timer.

#### ONE-SHOT mode

When the timer is disabled, the Timer Output signal is set to the value of this bit.

When the timer is enabled, the Timer Output signal is complemented upon timer Reload.

#### CONTINUOUS mode

When the timer is disabled, the Timer Output signal is set to the value of this bit.

When the timer is enabled, the Timer Output signal is complemented upon timer Reload.

#### COUNTER mode

If the timer is enabled the Timer Output signal is complemented after timer reload.

0 = Count occurs on the rising edge of the Timer Input signal.

1 = Count occurs on the falling edge of the Timer Input signal.

# Low Power Operational Amplifier

## Overview

The LPO is a general-purpose low power operational amplifier. Each of the three ports of the amplifier is accessible from the package pins. The LPO contains only one pin configuration: ANA0 is the output/feedback node, ANA1 is the inverting input and ANA2 is the non-inverting input.

## Operation

To use the LPO, it must be enabled in the [Power Control Register 0 \(PWRCTL0\)](#). The default state of the LPO is OFF. To use the LPO, the LPO bit must be cleared, turning it ON ([Power Control Register 0 \(PWRCTL0\)](#) on page 35). When making normal ADC measurements on ANA0 (measurements not involving the LPO output), the LPO bit must be OFF. Turning the LPO bit ON interferes with normal ADC measurements.



**Warning:** *The LPO bit enables the amplifier even in STOP mode. If the amplifier is not required in STOP mode, disable it. Failing to perform this results in STOP mode currents higher than necessary.*

As with other ADC measurements, any pins used for analog purposes must be configured as such in the GPIO registers (see [Port A–D Alternate Function Sub-Registers](#) on page 47).

LPO output measurements are made on ANA0, as selected by the ANAIN[3:0] bits of [ADC Control Register 0](#). It is also possible to make single-ended measurements on ANA1 and ANA2 while the amplifier is enabled, which is often useful for determining offset conditions. Differential measurements between ANA0 and ANA2 may be useful for noise cancellation purposes.

If the LPO output is routed to the ADC, then the BUFFMODE[2:0] bits of [ADC Control/Status Register 1](#) must also be configured for unity-gain buffered operation. Sampling the LPO in an unbuffered mode is not recommended.

When either input is overdriven, the amplifier output saturates at the positive or negative supply voltage. No instability results.





Assuming a compensated ADC measurement, the following equation defines the relationship between the ADC reading and the die temperature:

$$T = (25/128) \times (\text{ADC} - \text{TSCAL}[11:2]) + 30$$

where, T is the temperature in C; ADC is the 10-bit compensated ADC value; and TSCAL is the temperature sensor calibration value, ignoring the two least significant bits of the 12-bit value.

See [Temperature Sensor Calibration Data](#) on page 164 for the location of TSCAL.

## Calibration

The temperature sensor undergoes calibration during the manufacturing process and is maximally accurate at 30 °C. Accuracy decreases as measured temperatures move further from the calibration point.

## Flash Status Register

The Flash Status (FSTAT) register indicates the current state of the Flash Controller. This register can be read at any time. The read-only Flash Status register shares its Register File address with the Write-only Flash Control register.

**Table 79. Flash Status Register (FSTAT)**

BITS	7	6	5	4	3	2	1	0
FIELD	Reserved		FSTAT					
RESET	0	0	0	0	0	0	0	0
R/W	R	R	R	R	R	R	R	R
ADDR	FF8H							

Reserved—Must be 0.

FSTAT—Flash Controller Status

000000 = Flash Controller locked

000001 = First unlock command received (73H written)

000010 = Second unlock command received (8CH written)

000011 = Flash Controller unlocked

000100 = Sector protect register selected

001xxx = Program operation in progress

010xxx = Page erase operation in progress

100xxx = Mass erase operation in progress

## Flash Page Select Register

The Flash Page Select (FPS) register shares address space with the Flash Sector Protect Register. Unless the Flash controller is unlocked and written with 5EH, writes to this address target the Flash Page Select Register.

The register is used to select one of the available Flash memory pages to be programmed or erased. Each Flash Page contains 512 bytes of Flash memory. During a Page Erase operation, all Flash memory having addresses with the most significant 7 bits given by FPS[6:0] are chosen for program/erase operation.

**Table 104. NVDS Read Time (Continued)**

<b>Operation</b>	<b>Minimum Latency</b>	<b>Maximum Latency</b>
Read (128 byte array)	883	7609
Write (16 byte array)	4973	5009
Write (64 byte array)	4971	5013
Write (128 byte array)	4984	5023
Illegal Read	43	43
Illegal Write	31	31

If NVDS read performance is critical to your software architecture, there are some things you can do to optimize your code for speed, listed in order from most helpful to least helpful:

- Periodically refresh all addresses that are used. The optimal use of NVDS in terms of speed is to rotate the writes evenly among all addresses planned to use, bringing all reads closer to the minimum read time. Because the minimum read time is much less than the write time, however, actual speed benefits are not always realized.
- Use as few unique addresses as possible: this helps to optimize the impact of refreshing as well as minimize the requirement for it.

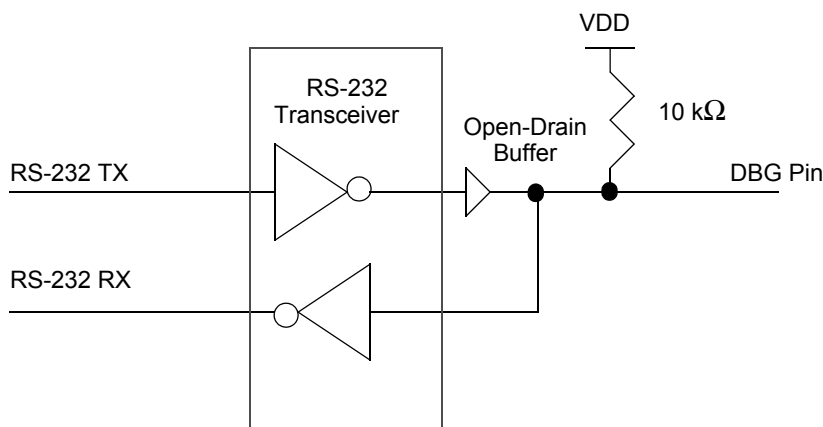


Figure 25. Interfacing the On-Chip Debugger's DBG Pin with an RS-232 Interface (2)

## DEBUG Mode

The operating characteristics of the devices in DEBUG mode are:

- The eZ8 CPU fetch unit stops, idling the eZ8 CPU, unless directed by the OCD to execute specific instructions.
- The system clock operates unless in STOP mode.
- All enabled on-chip peripherals operate unless in STOP mode.
- Automatically exits HALT mode.
- Constantly refreshes the Watchdog Timer, if enabled.

## Entering DEBUG Mode

The operating characteristics of the devices entering DEBUG mode are:

- The device enters DEBUG mode after the eZ8 CPU executes a BRK (Breakpoint) instruction.
- If the DBG pin is held Low during the final clock cycle of system reset, the part enters DEBUG mode immediately (20-/28-pin products only).

► **Note:** *Holding the DBG pin Low for an additional 5000 (minimum) clock cycles after reset (making sure to account for any specified frequency error if using an internal oscillator) prevents a false interpretation of an Autobaud sequence (see [OCD Auto-Baud Detector/Generator](#) on page 176).*

The Auto-Baud Detector/Generator is clocked by the system clock. The minimum baud rate is the system clock frequency divided by 512. For optimal operation with asynchronous datastreams, the maximum recommended baud rate is the system clock frequency divided by 8. The maximum possible baud rate for asynchronous datastreams is the system clock frequency divided by 4, but this theoretical maximum is possible only for low noise designs with clean signals. [Table 105](#) lists minimum and recommended maximum baud rates for sample crystal frequencies.

**Table 105. OCD Baud-Rate Limits**

System Clock Frequency (MHz)	Recommended Maximum Baud Rate (Kbps)	Recommended Standard PC Baud Rate (bps)	Minimum Baud Rate (Kbps)
20.0	2500.0	1,843,200	39
1.0	125.0	115,200	1.95
0.032768 (32 kHz)	4.096	2,400	0.064

If the OCD receives a Serial Break (nine or more continuous bits Low) the Auto-Baud Detector/Generator resets. Reconfigure the Auto-Baud Detector/Generator by sending 80H.

## OCD Serial Errors

The On-Chip Debugger can detect any of the following error conditions on the DBG pin:

- Serial Break (a minimum of nine continuous bits Low)
- Framing Error (received `stop` bit is Low)
- Transmit Collision (OCD and host simultaneous transmission detected by the OCD)

When the OCD detects one of these errors, it aborts any command currently in progress, transmits a four character long Serial Break back to the host, and resets the Auto-Baud Detector/Generator. A Framing Error or Transmit Collision may be caused by the host sending a Serial Break to the OCD. Because of the open-drain nature of the interface, returning a Serial Break back to the host only extends the length of the Serial Break if the host releases the Serial Break early.

The host transmits a Serial Break on the DBG pin when first connecting to the Z8 Encore! XP F082A Series devices or when recovering from an error. A Serial Break from the host resets the Auto-Baud Generator/Detector but does not reset the OCD Control register. A Serial Break leaves the device in DEBUG mode if that is the current mode. The OCD is held in Reset until the end of the Serial Break when the DBG pin returns

High. Because of the open-drain nature of the DBG pin, the host can send a Serial Break to the OCD even if the OCD is transmitting a character.

## OCD Unlock Sequence (8-Pin Devices Only)

Because of pin-sharing on the 8-pin device, an unlock sequence must be performed to access the DBG pin. If this sequence is not completed during a system reset, then the PA0/DBG pin functions only as a GPIO pin.

The following sequence unlocks the DBG pin:

1. Hold PA2/ $\overline{\text{RESET}}$  Low.
2. Wait 5ms for the internal reset sequence to complete.
3. Send the following bytes serially to the debug pin:  
DBG  $\leftarrow$  80H (autobaud)  
DBG  $\leftarrow$  EBH  
DBG  $\leftarrow$  5AH  
DBG  $\leftarrow$  70H  
DBG  $\leftarrow$  CDH (32-bit unlock key)
4. Release PA2/ $\overline{\text{RESET}}$ . The PA0/DBG pin is now identical in function to that of the DBG pin on the 20-/28-pin device. To enter DEBUG mode, re-autobaud and write 80H to the OCD control register (see [On-Chip Debugger Commands](#) on page 179).



**Caution:** *Between [Step 3](#) and [Step 4](#), there is an interval during which the 8-pin device is neither in RESET nor DEBUG mode. If a device has been erased or has not yet been programmed, all program memory bytes contain FFH. The CPU interprets this as an illegal instruction, so some irregular behavior can occur before entering DEBUG mode, and the register values after entering DEBUG mode differs from their specified reset values. However, none of these irregularities prevent programming the Flash memory. Before beginning system debug, it is recommended that some legal code be programmed into the 8-pin device, and that a RESET occurs.*

## Breakpoints

Execution Breakpoints are generated using the BRK instruction (opcode 00H). When the eZ8 CPU decodes a BRK instruction, it signals the On-Chip Debugger. If Breakpoints are enabled, the OCD enters DEBUG mode and idles the eZ8 CPU. If Breakpoints are not enabled, the OCD ignores the BRK signal and the BRK instruction operates as an NOP instruction.

Write Memory, Read Memory, Write Register, Read Register, Read Memory CRC, Step Instruction, Stuff Instruction, and Execute Instruction commands.

```
DBG ← 03H
DBG → RuntimeCounter[15:8]
DBG → RuntimeCounter[7:0]
```

- **Write OCD Control Register (04H)**—The Write OCD Control Register command writes the data that follows to the OCDCTL register. When the Flash Read Protect Option Bit is enabled, the DBGMODE bit (OCDCTL[7]) can only be set to 1, it cannot be cleared to 0 and the only method of returning the device to normal operating mode is to reset the device.

```
DBG ← 04H
DBG ← OCDCTL[7:0]
```

- **Read OCD Control Register (05H)**—The Read OCD Control Register command reads the value of the OCDCTL register.

```
DBG ← 05H
DBG → OCDCTL[7:0]
```

- **Write Program Counter (06H)**—The Write Program Counter command writes the data that follows to the eZ8 CPU's Program Counter (PC). If the device is not in DEBUG mode or if the Flash Read Protect Option bit is enabled, the Program Counter (PC) values are discarded.

```
DBG ← 06H
DBG ← ProgramCounter[15:8]
DBG ← ProgramCounter[7:0]
```

- **Read Program Counter (07H)**—The Read Program Counter command reads the value in the eZ8 CPU's Program Counter (PC). If the device is not in DEBUG mode or if the Flash Read Protect Option bit is enabled, this command returns FFFFH.

```
DBG ← 07H
DBG → ProgramCounter[15:8]
DBG → ProgramCounter[7:0]
```

- **Write Register (08H)**—The Write Register command writes data to the Register File. Data can be written 1–256 bytes at a time (256 bytes can be written by setting size to 0). If the device is not in DEBUG mode, the address and data values are discarded. If the Flash Read Protect Option bit is enabled, only writes to the Flash Control Registers are allowed and all other register write data values are discarded.

```
DBG ← 08H
DBG ← {4'h0, Register Address[11:8]}
DBG ← Register Address[7:0]
DBG ← Size[7:0]
DBG ← 1-256 data bytes
```

## Assembly Language Syntax

For proper instruction execution, eZ8 CPU assembly language syntax requires that the operands be written as ‘destination, source’. After assembly, the object code usually has the operands in the order ‘source, destination’, but ordering is opcode-dependent. The following instruction examples illustrate the format of some basic assembly instructions and the resulting object code produced by the assembler. This binary format must be followed if manual program coding is preferred or if you intend to implement your own assembler.

**Example 1:** If the contents of Registers 43H and 08H are added and the result is stored in 43H, the assembly syntax and resulting object code is:

**Table 112. Assembly Language Syntax Example 1**

<b>Assembly Language Code</b>	ADD	43H,	08H	(ADD dst, src)
<b>Object Code</b>	04	08	43	(OPC src, dst)

**Example 2:** In general, when an instruction format requires an 8-bit register address, that address can specify any register location in the range 0–255 or, using Escaped Mode Addressing, a Working Register R0–R15. If the contents of Register 43H and Working Register R8 are added and the result is stored in 43H, the assembly syntax and resulting object code is:

**Table 113. Assembly Language Syntax Example 2**

<b>Assembly Language Code</b>	ADD	43H,	R8	(ADD dst, src)
<b>Object Code</b>	04	E8	43	(OPC src, dst)

See the device-specific Product Specification to determine the exact register file range available. The register file size varies, depending on the device type.

## eZ8 CPU Instruction Notation

In the eZ8 CPU Instruction Summary and Description sections, the operands, condition codes, status flags, and address modes are represented by a notational shorthand that is described in [Table 114](#).



		Lower Nibble (Hex)																
		0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F	
Upper Nibble (Hex)	0	1.1 BRK	2.2 SRP	2.3 ADD	2.4 ADD	3.3 ADD	3.4 ADD	3.3 ADD	3.4 ADD	4.3 ADDX	4.3 ADDX	2.3 DJNZ	2.2 JR	2.2 LD	3.2 JP	1.2 INC	1.2 NOP	
	1	2.2 RLC	2.3 RLC	2.3 ADC	2.4 ADC	3.3 ADC	3.4 ADC	3.3 ADC	3.4 ADC	4.3 ADCX	4.3 ADCX							See 2nd Opcode Map
	2	2.2 INC	2.3 INC	2.3 SUB	2.4 SUB	3.3 SUB	3.4 SUB	3.3 SUB	3.4 SUB	4.3 SUBX	4.3 SUBX							1, 2 ATM
	3	2.2 DEC	2.3 DEC	2.3 SBC	2.4 SBC	3.3 SBC	3.4 SBC	3.3 SBC	3.4 SBC	4.3 SBCX	4.3 SBCX							
	4	2.2 DA	2.3 DA	2.3 OR	2.4 OR	3.3 OR	3.4 OR	3.3 OR	3.4 OR	4.3 ORX	4.3 ORX							
	5	2.2 POP	2.3 POP	2.3 AND	2.4 AND	3.3 AND	3.4 AND	3.3 AND	3.4 AND	4.3 ANDX	4.3 ANDX							1.2 WDT
	6	2.2 COM	2.3 COM	2.3 TCM	2.4 TCM	3.3 TCM	3.4 TCM	3.3 TCM	3.4 TCM	4.3 TCMX	4.3 TCMX							1.2 STOP
	7	2.2 PUSH	2.3 PUSH	2.3 TM	2.4 TM	3.3 TM	3.4 TM	3.3 TM	3.4 TM	4.3 TMX	4.3 TMX							1.2 HALT
	8	2.5 DECW	2.6 DECW	2.5 LDE	2.9 LDEI	3.2 LDX	3.3 LDX	3.4 LDX	3.5 LDX	3.4 LDX	3.4 LDX							1.2 DI
	9	2.2 RL	2.3 RL	2.5 LDE	2.9 LDEI	3.2 LDX	3.3 LDX	3.4 LDX	3.5 LDX	3.3 LEA	3.5 LEA							1.2 EI
	A	2.5 INCW	2.6 INCW	2.3 CP	2.4 CP	3.3 CP	3.4 CP	3.3 CP	3.4 CP	4.3 CPX	4.3 CPX							1.4 RET
	B	2.2 CLR	2.3 CLR	2.3 XOR	2.4 XOR	3.3 XOR	3.4 XOR	3.3 XOR	3.4 XOR	4.3 XORX	4.3 XORX							1.5 IRET
	C	2.2 RRC	2.3 RRC	2.5 LDC	2.9 LDCI	2.3 JP	2.9 LDC		3.4 LD	3.2 PUSHX								1.2 RCF
	D	2.2 SRA	2.3 SRA	2.5 LDC	2.9 LDCI	2.6 CALL	2.2 BSWAP	3.3 CALL	3.4 LD	3.2 POPX								1.2 SCF
	E	2.2 RR	2.3 RR	2.2 BIT	2.3 LD	3.2 LD	3.3 LD	3.2 LD	3.3 LD	4.2 LDX	4.2 LDX							1.2 CCF
	F	2.2 SWAP	2.3 SWAP	2.6 TRAP	2.3 LD	2.8 MULT	3.3 LD	3.3 BTJ	3.4 BTJ									

Figure 31. First Opcode Map

# Electrical Characteristics

The data in this chapter is pre-qualification and pre-characterization and is subject to change. Additional electrical characteristics may be found in the individual chapters.

## Absolute Maximum Ratings

Stresses greater than those listed in [Table 126](#) may cause permanent damage to the device. These ratings are stress ratings only. Operation of the device at any condition outside those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. For improved reliability, tie unused inputs to one of the supply voltages ( $V_{DD}$  or  $V_{SS}$ ).

**Table 126. Absolute Maximum Ratings**

Parameter	Minimum	Maximum	Units	Notes
Ambient temperature under bias	-40	+105	°C	
Storage temperature	-65	+150	°C	
Voltage on any pin with respect to $V_{SS}$	-0.3	+5.5	V	<a href="#">1</a>
	-0.3	+3.9	V	<a href="#">2</a>
Voltage on $V_{DD}$ pin with respect to $V_{SS}$	-0.3	+3.6	V	
Maximum current on input and/or inactive output pin	-5	+5	μA	
Maximum output current from active output pin	-25	+25	mA	
<b>8-pin Packages Maximum Ratings at 0 °C to 70 °C</b>				
Total power dissipation		220	mW	
Maximum current into $V_{DD}$ or out of $V_{SS}$		60	mA	
<b>20-pin Packages Maximum Ratings at 0 °C to 70 °C</b>				
Total power dissipation		430	mW	
Maximum current into $V_{DD}$ or out of $V_{SS}$		120	mA	

**Table 126. Absolute Maximum Ratings (Continued)**

Parameter	Minimum	Maximum	Units	Notes
<b>28-pin Packages Maximum Ratings at 0 °C to 70 °C</b>				
Total power dissipation		450	mW	
Maximum current into $V_{DD}$ or out of $V_{SS}$		125	mA	
Operating temperature is specified in DC Characteristics.				
1. This voltage applies to all pins except the following: $V_{DD}$ , $AV_{DD}$ , pins supporting analog input (Port B[5:0], Port C[2:0]) and pins supporting the crystal oscillator (PA0 and PA1). On the 8-pin packages, this applies to all pins but $V_{DD}$ . 2. This voltage applies to pins on the 20-/28-pin packages supporting analog input (Port B[5:0], Port C[2:0]) and pins supporting the crystal oscillator (PA0 and PA1).				

## DC Characteristics

Table 127 lists the DC characteristics of the Z8 Encore! XP<sup>®</sup> F082A Series products. All voltages are referenced to  $V_{SS}$ , the primary system ground.

**Table 127. DC Characteristics**

Symbol	Parameter	$T_A = -40\text{ °C to }+105\text{ °C}$ (unless otherwise specified)			Units	Conditions
		Minimum	Typical	Maximum		
$V_{DD}$	Supply Voltage	2.7	–	3.6	V	
$V_{IL1}$	Low Level Input Voltage	-0.3	–	$0.3 \cdot V_{DD}$	V	
$V_{IH1}$	High Level Input Voltage	$0.7 \cdot V_{DD}$	–	5.5	V	For all input pins without analog or oscillator function. For all signal pins on the 8-pin devices. Programmable pull-ups must also be disabled.
$V_{IH2}$	High Level Input Voltage	$0.7 \cdot V_{DD}$	–	$V_{DD} + 0.3$	V	For those pins with analog or oscillator function (20-/28-pin devices only), or when programmable pull-ups are enabled.
$V_{OL1}$	Low Level Output Voltage	–	–	0.4	V	$I_{OL} = 2\text{ mA}$ ; $V_{DD} = 3.0\text{ V}$ High Output Drive disabled.
$V_{OH1}$	High Level Output Voltage	2.4	–	–	V	$I_{OH} = -2\text{ mA}$ ; $V_{DD} = 3.0\text{ V}$ High Output Drive disabled.

## Ordering Information

Order the Z8 Encore! XP<sup>®</sup> F082A Series from Zilog<sup>®</sup>, using the following part numbers. For more information on ordering, please consult your local Zilog sales office. The Zilog website ([www.zilog.com](http://www.zilog.com)) lists all regional offices and provides additional Z8 Encore! XP product information.

Part Number	Flash	RAM	NVDS	I/O Lines	Interrupts	16-Bit Timers w/PWM	10-Bit A/D Channels	UART with IrDA	Comparator	Temperature Sensor	Description
<b>Z8 Encore! XP<sup>®</sup> F082A Series with 8 KB Flash, 10-Bit Analog-to-Digital Converter</b>											
<b>Standard Temperature: 0 °C to 70 °C</b>											
Z8F082APB020SC	8 KB	1 KB	0	6	14	2	4	1	1	1	PDIP 8-pin package
Z8F082AQB020SC	8 KB	1 KB	0	6	14	2	4	1	1	1	QFN 8-pin package
Z8F082ASB020SC	8 KB	1 KB	0	6	14	2	4	1	1	1	SOIC 8-pin package
Z8F082ASH020SC	8 KB	1 KB	0	17	20	2	7	1	1	1	SOIC 20-pin package
Z8F082AHH020SC	8 KB	1 KB	0	17	20	2	7	1	1	1	SSOP 20-pin package
Z8F082APH020SC	8 KB	1 KB	0	17	20	2	7	1	1	1	PDIP 20-pin package
Z8F082ASJ020SC	8 KB	1 KB	0	23	20	2	8	1	1	1	SOIC 28-pin package
Z8F082AHJ020SC	8 KB	1 KB	0	23	20	2	8	1	1	1	SSOP 28-pin package
Z8F082APJ020SC	8 KB	1 KB	0	23	20	2	8	1	1	1	PDIP 28-pin package
<b>Extended Temperature: -40 °C to 105 °C</b>											
Z8F082APB020EC	8 KB	1 KB	0	6	14	2	4	1	1	1	PDIP 8-pin package
Z8F082AQB020EC	8 KB	1 KB	0	6	14	2	4	1	1	1	QFN 8-pin package
Z8F082ASB020EC	8 KB	1 KB	0	6	14	2	4	1	1	1	SOIC 8-pin package
Z8F082ASH020EC	8 KB	1 KB	0	17	20	2	7	1	1	1	SOIC 20-pin package
Z8F082AHH020EC	8 KB	1 KB	0	17	20	2	7	1	1	1	SSOP 20-pin package
Z8F082APH020EC	8 KB	1 KB	0	17	20	2	7	1	1	1	PDIP 20-pin package
Z8F082ASJ020EC	8 KB	1 KB	0	23	20	2	8	1	1	1	SOIC 28-pin package
Z8F082AHJ020EC	8 KB	1 KB	0	23	20	2	8	1	1	1	SSOP 28-pin package
Z8F082APJ020EC	8 KB	1 KB	0	23	20	2	8	1	1	1	PDIP 28-pin package
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